TPS76130, TPS76132, TPS76133, TPS76138, TPS76150 LOW-POWER 100-mA LOW-DROPOUT LINEAR REGULATORS

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- 100-mA Low-Dropout Regulator
- Fixed Output Voltage Options: 5 V, 3.8 V, 3.3 V, 3.2 V, and 3 V
- Dropout Typically 170 mV at 100-mA
- Thermal Protection
- Less Than 1 μA Quiescent Current in Shutdown
- −40°C to 125°C Operating Junction Temperature Range
- 5-Pin SOT-23 (DBV) Package
- ESD Protection Verified to 1.5 KV Human Body Model (HBM) per MIL-STD-883C

DBV PACKAGE (TOP VIEW) EN GND IN 3 2 1 4 5 NC OUT

NC - No internal connection

description

The TPS761xx is a 100 mA, low dropout (LDO) voltage regulator designed specifically for battery-powered applications. A proprietary BiCMOS fabrication process allows the TPS761xx to provide outstanding performance in all specifications critical to battery-powered operation.

The TPS761xx is available in a space-saving SOT-23 (DBV) package and operates over a junction temperature range of –40°C to 125°C.

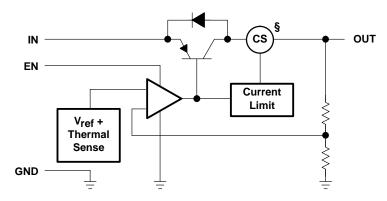
AVAILABLE OPTIONS

| TJ | VOLTAGE | PACKAGE | PART N | SYMBOL | | |
|----------------|---------|-----------------|---------------------------|---------------------------|---------------|------|
| | 3 V | | TPS76130DBVR [†] | TPS76130DBVT‡ | PAEI | |
| -40°C to 125°C | 3.2 V | SOT-23 (DBV) | TPS76132DBVR [†] | TPS76132DBVT‡ | PAFI | |
| | 3.3 V | | | TPS76133DBVR [†] | TPS76133DBVT‡ | PAII |
| | 3.8 V | | TPS76138DBVR [†] | TPS76138DBVT‡ | PAKI | |
| | 5 V | | TPS76150DBVR† | TPS76150DBVT‡ | PALI | |

[†]The DBVR passive indicates tape and reel of 3000 parts.

§ Current sense

functional block diagram





Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



[‡]The DBVT passive indicates tape and reel of 250 parts.

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Terminal Functions

| TERM | INAL | 1/0 | DESCRIPTION | | | | | | |
|------|------|-----|--------------------------|--|--|--|--|--|--|
| NAME | NO. | 1/0 | DESCRIPTION | | | | | | |
| EN | 3 | I | Enable input | | | | | | |
| GND | 2 | | Ground | | | | | | |
| IN | 1 | I | Input voltage | | | | | | |
| NC | 4 | | No connection | | | | | | |
| OUT | 5 | 0 | Regulated output voltage | | | | | | |

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| Input voltage range, V _I (see Note 1) | –0.3 V to 16 V |
|--|---------------------------------|
| Voltage range at EN | 0.3 V to V _I + 0.3 V |
| Peak output current | internally limited |
| Continuous total dissipation | See Dissipation Rating Table |
| Operating junction temperature range, T _J | –40°C to 150°C |
| Storage temperature range, T _{stq} | –65°C to 150°C |
| ESD rating, HBM | |

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to device GND pin.

DISSIPATION RATING TABLE

| BOARD | PACKAGE | $R_{	heta}$ JC | $R_{	heta JA}$ | DERATING FACTOR ABOVE T _A = 25°C | $T_{\mbox{$A$}} \leq 25^{\circ}\mbox{$C$}$ POWER RATING | T _A = 70°C POWER RATING | T _A = 85°C POWER RATING |
|---------|---------|----------------|----------------|--|---|---------------------------------------|---------------------------------------|
| Low K‡ | DBV | 65.8 °C/W | 259 °C/W | 3.9 mW/°C | 386 mW | 212 mW | 154 mW |
| High K§ | DBV | 65.8 °C/W | 180 °C/W | 5.6 mW/°C | 555 mW | 305 mW | 222 mW |

[‡] The JEDEC Low K (1s) board design used to derive this data was a 3 inch x 3 inch, two layer board with 2 ounce copper traces on top of the board. § The JEDEC High K (2s2p) board design used to derive this data was a 3 inch x 3 inch, multilayer board with 1 ounce internal power and ground planes and 2 ounce copper traces on top and bottom of the board.

recommended operating conditions

| | | MIN | NOM MAX | UNIT |
|-------------------------------|----------|------|---------|------|
| | TPS76130 | 3.35 | 16 | |
| | TPS76132 | 3.58 | 16 | |
| Input voltage, V _I | TPS76133 | 3.68 | 16 | V |
| | TPS76138 | 4.18 | 16 | |
| | TPS76150 | 5.38 | 16 | |
| Continuous output current, Id |) | 0 | 100 | mA |
| Operating junction temperate | ure, TJ | -40 | 125 | °C |

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electrical characteristics over recommended operating free-air temperature range, $V_I = V_{O(typ)} + 1 \text{ V}$, $I_O = 1 \text{ mA}$, $EN = V_I$, $C_O = 4.7 \, \mu\text{F}$ (unless otherwise noted)

| PARAMETER | | | TEST CONDITIONS | | MIN | TYP | MAX | UNIT | | |
|----------------------------|----------------------|--------------|---|--|------|------|------|-------|--|--|
| | | | T _J = 25°C | | 2.96 | 3 | 3.04 | | | |
| | | TPS76130 | T _J = 25°C, | 1 mA < I _O < 100 mA | 2.9 | | 3.04 | V | | |
| | | | 1 mA < I _O < 100 mA | | 2.89 | | 3.07 | | | |
| | | | $T_{J} = 25^{\circ}C$ 3.16 | | 3.2 | 3.24 | | | | |
| | | TPS76132 | T _J = 25°C, | 1 mA < I _O < 100 mA | 3.11 | | 3.24 | V | | |
| | | | 1 mA < I _O < 100 mA | | 3.08 | | 3.3 | | | |
| | | | T _J = 25°C | | 3.26 | 3.3 | 3.34 | | | |
| ٧o | Output voltage | TPS76133 | T _J = 25°C, | 1 mA < I _O < 100 mA | 3.21 | | 3.34 | V | | |
| | | | 1 mA < I _O < 100 mA | | 3.18 | | 3.4 | | | |
| | | | T _J = 25°C | | 3.76 | 3.8 | 3.84 | | | |
| | | TPS76138 | T _J = 25°C, | 1 mA < I _O < 100 mA | 3.71 | | 3.84 | V | | |
| | | | 1 mA < I _O < 100 mA | | 3.68 | | 3.9 | | | |
| | | | T _J = 25°C | | 4.95 | 5 | 5.05 | | | |
| | | TPS76150 | T _J = 25°C, | 1 mA < I _O < 100 mA | 4.88 | | 5.05 | V | | |
| | | | 1 mA < I _O < 100 mA | | 4.86 | | 5.1 | | | |
| I(standby) Standby current | | | EN = 0 V | | | | 1 | μΑ | | |
| | | | $I_O = 0 \text{ mA},$ | T _J = 25°C | | 90 | 115 | | | |
| | | | $I_O = 0 \text{ mA}$ | | | 130 | | | | |
| | | | $I_O = 1 \text{ mA},$ | T _J = 25°C | | 100 | 130 | | | |
| | | | I _O = 1 mA | | | | 170 | | | |
| | 0: | NID () | I _O = 10 mA, | T _J = 25°C | | 190 | 220 | 1 . ! | | |
| | Quiescent current (G | SND current) | I _O = 10 mA | | | | 260 | μΑ | | |
| | | | I _O = 50 mA, | T _J = 25°C | | 850 | 1100 | | | |
| | | | I _O = 50 mA | | | | 1200 | | | |
| | | | I _O = 100 mA, | T _J = 25°C | | 2600 | 3600 | | | |
| | | | I _O = 100 mA | | | | 4000 | | | |
| | | TPS76130 | 4 V < V _I < 16, | I _O = 1 mA | | 3 | 10 | | | |
| | | TPS76132 | 4.2 V < V _I < 16, | I _O = 1 mA | | 3 | 10 | | | |
| | Input regulation | TPS76133 | 4.3 V < V _I < 16, | I _O = 1 mA | | 3 | 10 | mV | | |
| | - | TPS76138 | 4.8 V < V _I < 16, | I _O = 1 mA | | 3 | 10 | 1 | | |
| | | TPS76150 | 6 V < V _I < 16 | I _O = 1 mA | | 3 | 10 | | | |
| Vn | Output noise voltage | | BW = 300 Hz to 50 kHz | $C_0 = 10 \mu\text{F}, \text{T}_J = 25^{\circ}\text{C}$ | | 190 | | μVrms | | |
| | Ripple rejection | | $f = 1 \text{ kHz}, C_0 = 10 \mu\text{F},$ | | | 63 | | dB | | |

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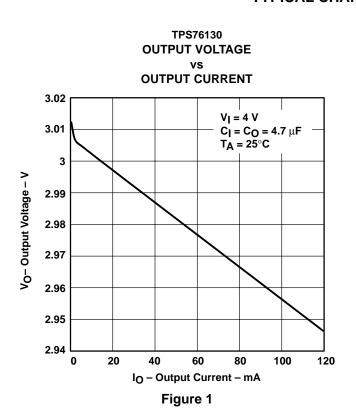
electrical characteristics over recommended operating free-air temperature range, $V_I = V_{O(typ)} + 1 \text{ V}$, $I_O = 1 \text{ mA}$, $EN = V_I$, $C_O = 4.7 \, \mu\text{F}$ (unless otherwise noted) (continued)

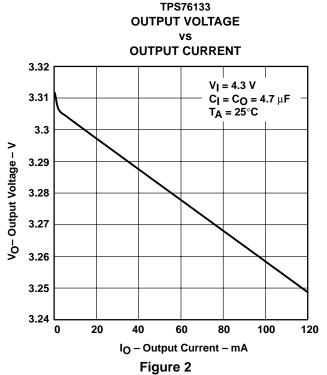
| PARAMETER | TEST CONDITIONS | MIN TYP | MAX | UNIT | | | | |
|-----------------------------------|--|---------|-----|------|--|--|--|--|
| | $I_O = 0 \text{ mA},$ $T_J = 25^{\circ}\text{C}$ | 1 | 3 | | | | | |
| | $I_O = 0 \text{ mA}$ | | 5 | | | | | |
| | $I_O = 1 \text{ mA},$ $T_J = 25^{\circ}\text{C}$ | 7 | 10 | mV | | | | |
| | I _O = 1 mA | | 15 | | | | | |
| Dropout voltage | $I_O = 10 \text{ mA},$ $T_J = 25^{\circ}\text{C}$ | 40 | 60 | | | | | |
| Dropout voltage | I _O = 10 mA | | 90 | | | | | |
| | $I_O = 50 \text{ mA},$ $T_J = 25^{\circ}\text{C}$ | 120 | 150 | | | | | |
| | I _O = 50 mA | | 180 | | | | | |
| | $I_{O} = 100 \text{ mA}, 	 T_{J} = 25^{\circ}\text{C}$ | 170 | 240 | | | | | |
| | I _O = 100 mA | | 280 | | | | | |
| Peak output current/current limit | | 100 125 | 135 | mA | | | | |
| High level enable input | | 2 | | V | | | | |
| Low level enable input | | | 0.8 | V | | | | |
| I. Input current (FNI) | EN = 0 V | -1 0 | 1 | | | | | |
| I _I Input current (EN) | EN = V _I | 2.5 | 5 | μA | | | | |

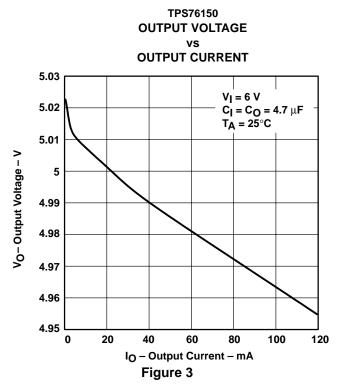
TYPICAL CHARACTERISTICS

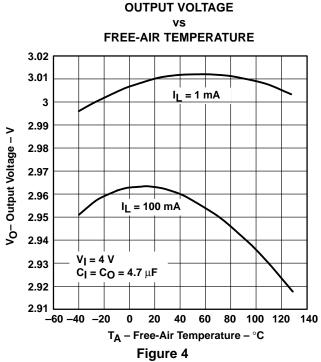
Table of Graphs

| | | | FIGURE |
|-----------------|-------------------------|-------------------------|---------|
| \/ ₋ | Output voltage | vs Output current | 1, 2, 3 |
| Vo | Output voltage | vs Free-air temperature | 4, 5, 6 |
| | Ground current | vs Free-air temperature | 7, 8, 9 |
| | Output noise | vs Frequency | 10 |
| Zo | Output impedance | vs Frequency | 11 |
| VDO | Dropout voltage | vs Free-air temperature | 12 |
| | Line transient response | | 13, 15 |
| | Load transient response | | 14, 16 |

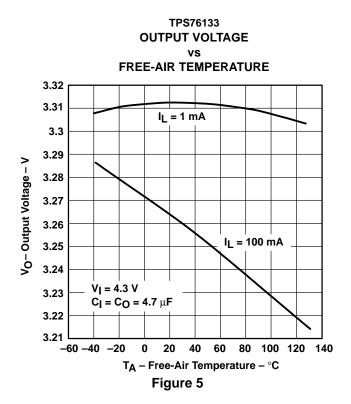


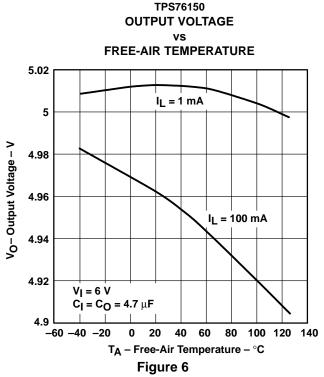






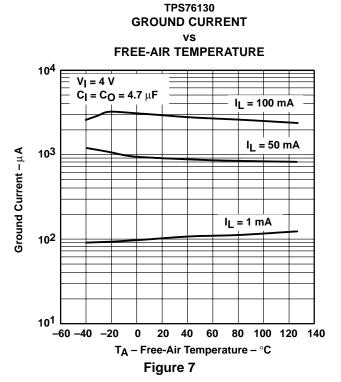
TPS76130

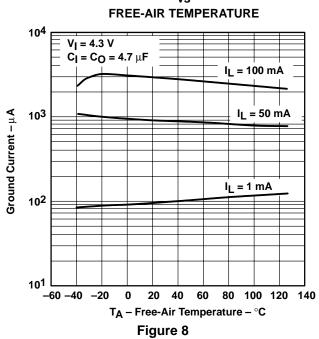


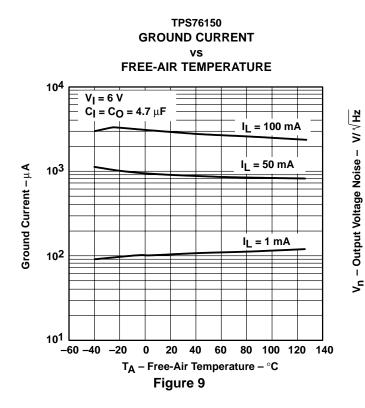


TPS76133

GROUND CURRENT







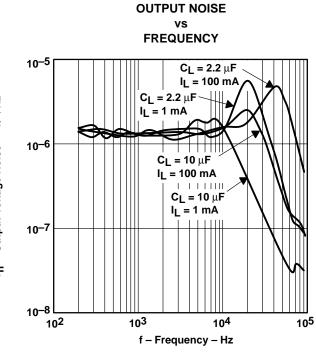
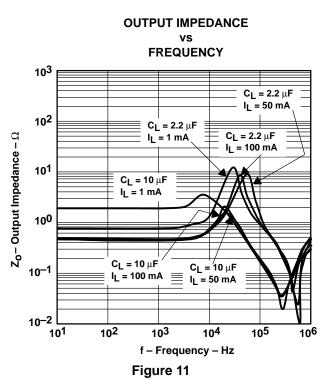
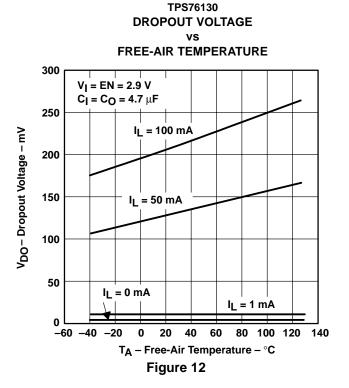


Figure 10





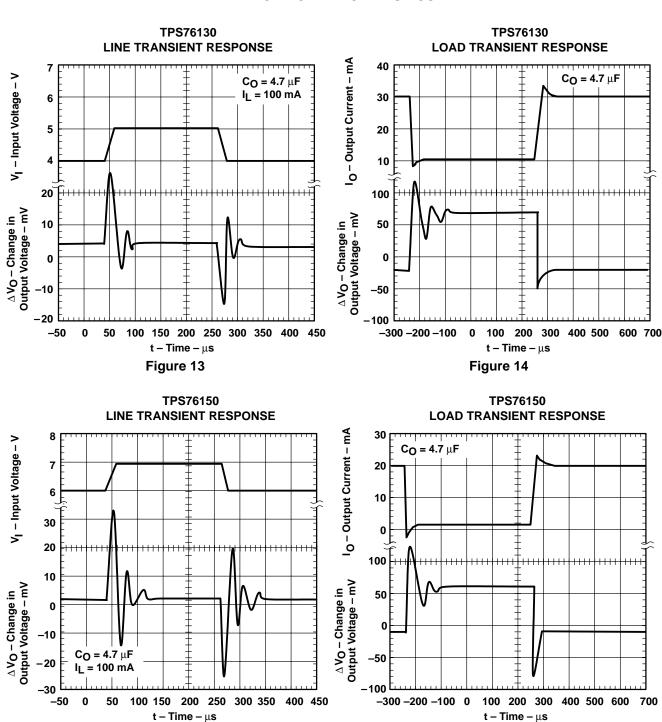




Figure 16

Figure 15

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APPLICATION INFORMATION

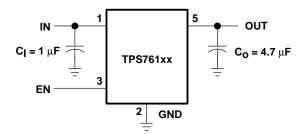


Figure 17. TPS761xx Typical Application

over current protection

The over current protection circuit forces the TPS761xx into a constant current output mode when the load is excessive or the output is shorted to ground. Normal operation resumes when the fault condition is removed.

NOTE:

An overload or short circuit may also activate the over temperature protection if the fault condition persists.

over temperature protection

The thermal protection system shuts the TPS761xx down when the junction temperature exceeds 160°C. The device recovers and operates normally when the temperature drops below 150°C.

input capacitor

A 1- μ F or larger ceramic decoupling capacitor with short leads connected between IN and GND is recommended. The decoupling capacitor may be omitted if there is a 1 μ F or larger electrolytic capacitor connected between IN and GND and located reasonably close to the TPS761xx. However, the small ceramic device is desirable even when the larger capacitor is present, if there is a lot of high frequency noise present in the system.

output capacitor

Like all low dropout regulators, the TPS761xx requires an output capacitor connected between OUT and GND to stabilize the internal control loop. The minimum recommended capacitance value is 4.7 μ F and the ESR (equivalent series resistance) must be between 0.1 Ω and 10 Ω . Solid tantalum electrolytic, aluminum electrolytic, and multilayer ceramic capacitors are all suitable, provided they meet the requirements described above. Most of the commercially available 4.7- μ F surface-mount solid-tantalum capacitors, including devices from Sprague, Kemet, and Nichicon, meet the ESR requirements stated above. Multilayer ceramic capacitors should have minimum values of 4.7 μ F over the full operating temperature range of the equipment.

enable (EN)

A logic zero on the enable input shuts the TPS761xx off and reduces the supply current to less than 1 μ A. Pulling the enable input high causes normal operation to resume. If the enable feature is not used, EN should be connected to IN to keep the regulator on all of the time. The EN input must not be left floating.

reverse current path

The power transistor used in the TPS761xx has an inherent diode connected between IN and OUT as shown in the functional block diagram. This diode conducts current from the OUT terminal to the IN terminal whenever IN is lower than OUT by a diode drop. This condition does not damage the TPS761xx provided the current is limited to 150 mA.

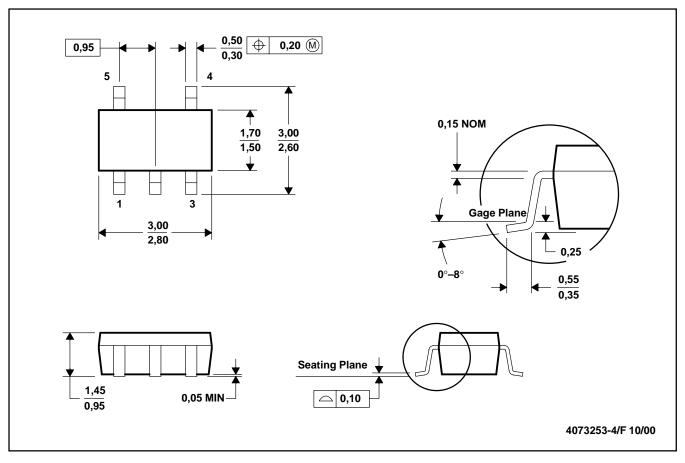


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MECHANICAL DATA

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion.
- D. Falls within JEDEC MO-178







PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | e Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|------------------|-----------------------|-----------------|--------------------|------|----------------|---------------------------|------------------|------------------------------|
| TPS76130DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76130DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76130DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76130DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76132DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76132DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76132DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76132DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76133DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76133DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76133DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76133DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76138DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76138DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76138DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76138DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76150DBVR | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76150DBVRG4 | ACTIVE | SOT-23 | DBV | 5 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76150DBVT | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| TPS76150DBVTG4 | ACTIVE | SOT-23 | DBV | 5 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |

(1) The marketing status values are defined as follows: **ACTIVE:** Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available. **OBSOLETE:** TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.



PACKAGE OPTION ADDENDUM

5-Feb-2007

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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Mailing Address: Texas Instruments

Post Office Box 655303 Dallas, Texas 75265